 國家實驗研究院 台灣半導體研究中心 Taiwan Semiconductor Research Institute		DOCUMENT NO. : Q3-NL04	TITLE : 設備作業標準 (CF-E09 ICP Etcher-感應耦合式電漿蝕刻機)		
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Deep-Si ICP Etcher


Standard Operating Procedures

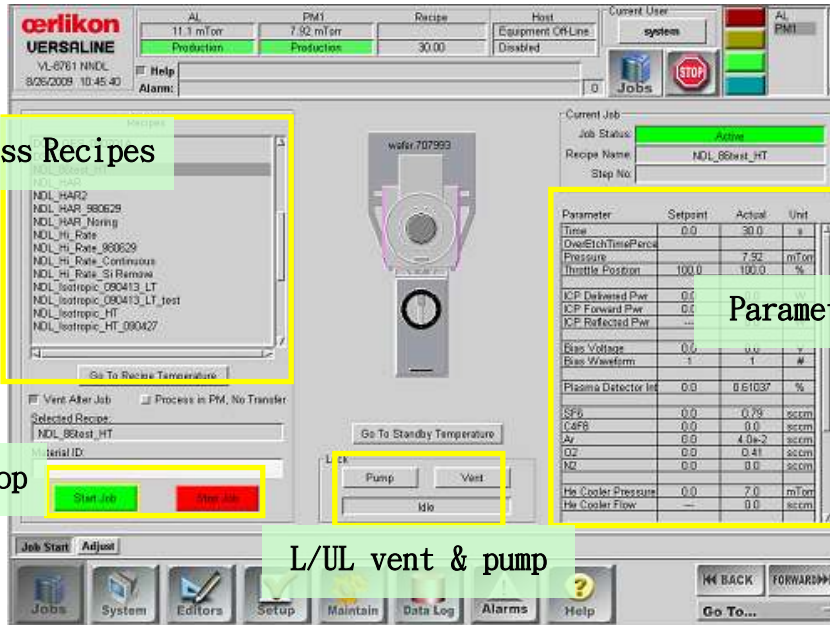
一、 Equipment introduction:



二、 Operate :

Main monitor.

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Jobs: Main page

System: Start or shutdown machine (Engineer only)

Editors: Recipe editor

Setup: Machine parameter setup (Engineer only)

Maintain: For maintain control (Engineer only)

Data Log: History data

Alarms: to show alarm message and exclude



Help: Direction


1. Check machine status (Green or Red)

2. Select recipe and put  .

3. Prepare samples .


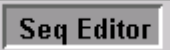

4. Press the button  to vent load-lock chamber · open cover

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and put wafer · close cover · press the button  to pump down ·



5. In to this page  and press Seq-Editor

   · load recipe and edit parameters ·

Remember save ·

6. Go to Loop editor    to setup loop times ·

7. Back to Job monitor · press the button  to start process ·



8. After process · clean chamber (Recipe: Clean_HT) ·

9. After chamber clean · pump down load-lock chamber ·

10. Finished ·

≡ · Please pay attention to the following points

1. When using HAR process · Loops limits ≤ 200 loops ·

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2. Every 300 Loops · clean chamber one time. (Recipe: Clean_HT 300 sec) °
3. When using Isotropic process · Time limits <= 300 sec per times °
4. After using · please pump down Load-Lock chamber °

In order to make the machine work smoothly, please operate according to the regulations °